

AP Memory Company Profile

AP Memory at a Glance

A Fabless Design Company Providing Customized Memory and IP Solutions

Founded in
2011

Headquarters in
Taiwan

230+
Employees

2016
Listed in TWSE (6531)

>9B
Unit Shipped

20+yr
Design Experience

USD 182M
2025 Revenue

Bringing Innovation to Reality



2017-2019

PSRAM for wafer-level packaging in wearables

Discrete DRAM-based Silicon Capacitors (^[2] S-SiCap™)

Ultra-High-Speed (UHS) PSRAM for display



2024-2026

S-SiCap™ interposer, S-SiCap™ embedded in substrates

ApSRAM™ for high-performance battery-powered edge devices

2011-2014

^[1] PSRAM for system-in-package in mobile phones

Low-pin-count (QSPI/OPI) PSRAM for IoT application



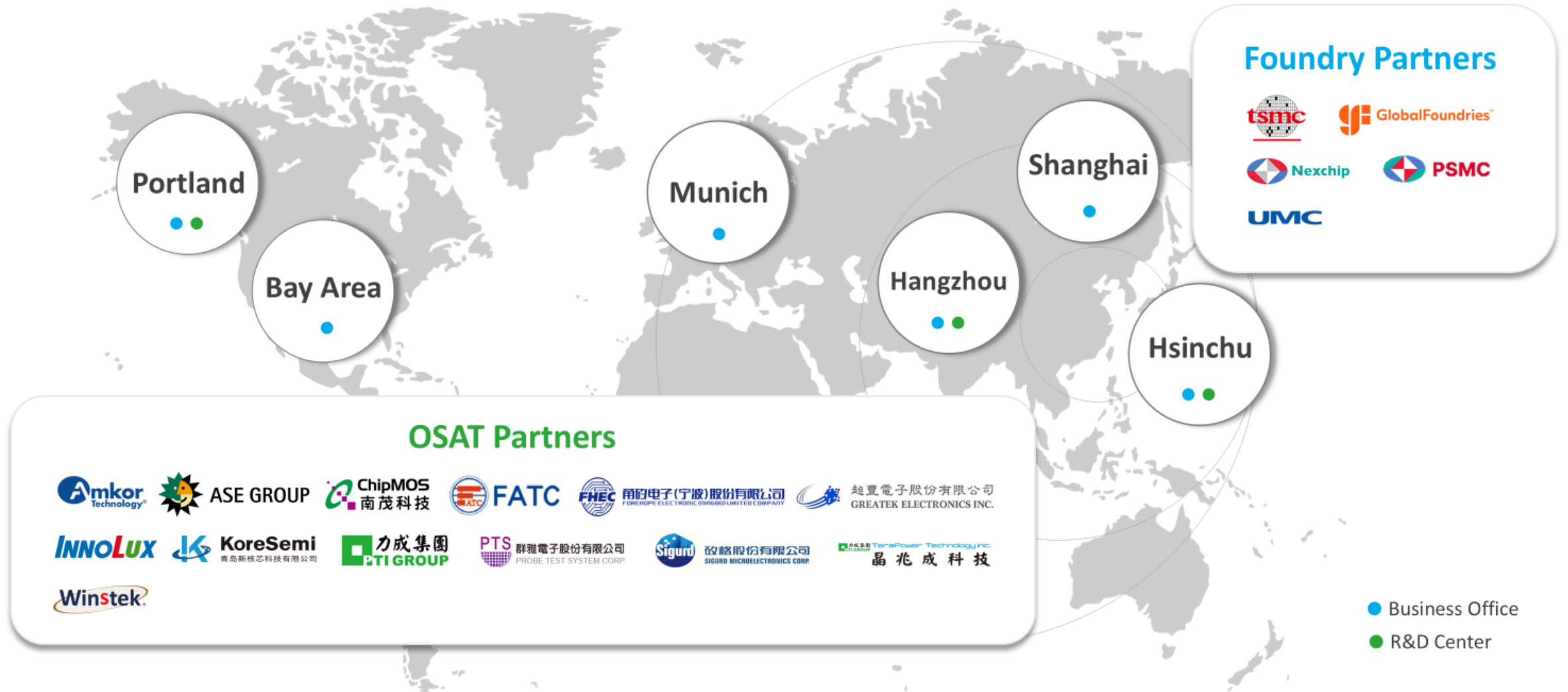
2020-2023

3D integrated DRAM and SoC (^[3] VHM™)

VHMStack™ PoC and Product design-ins



Global Presence and Supply Partners



An Overview of **AP Memory Products**

IoTRAM™

The Ideal Memory for IoT

Leading in product innovation and market share



Wearable



Smart Lock



LTE Modem

VHM™

The AI/HPC Memory Solution

World's first 3D integration of DRAM and SoC chips



AI Servers



Edge AI



HPC

S-SiCap™

The Performance Enabler

Highest capacitance density for high performance applications



AI Servers



HPC



Smartphone

Business Model



IoTRAM™ Portfolio

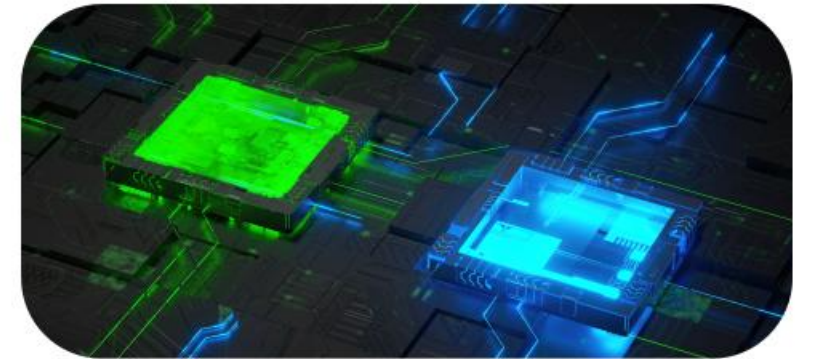
- >90% in Known-Good-Die (KGD) and WLCSP sales

VHM™ Memory Solution

- Design phase: NRE & Licensing of VHM™ IP
- Production phase: Royalty-like VHM™ DRAM wafer sales

S-SiCap™ IP & Products

- Discrete IC and interposers
- IP licensing & Royalty
- Design service and wafer sales



Broad Business Partner Network

SoC Partners



IP Partners



Distributors and Sales Representatives



Job Vacancies I

Working location: AP Memory Headquarters, Zhubei, Hsinchu, Taiwan
10F-1, No. 1, Taiyuan 1st St., Zhubei City, Hsinchu County 30288

Role	(1). Product Engineer	(2). Product Test Engineer
Scope	1. Conduct new product validation, characterization, and testing. 2. Perform design functionality verification and electrical analysis. 3. Analyze and characterize new product performance and specifications.	1. Develop and maintain CP/FT test programs for memory products on Advantest platforms. 2. Support new product validation and qualification activities. 3. Improve test program yield, test coverage, and stability. 4. Analyze and resolve production test yield issues for mass production products.
Requirements	-Fresh with Master's degree in Electrical Engineering (EE), Computer Science (CS), or a related field. -Good ability in using Advantest (T5503,T5593, T5583) to test.	Be skilled in (1)Unix (2)Solaris (3)C Language or Python (4)memory test-Advantest are plus.

Job Vacancies II

Working location: AP Memory Headquarters, Zhubei, Hsinchu, Taiwan
10F-1, No. 1, Taiyuan 1st St., Zhubei City, Hsinchu County 30288

Role	(3). RD-Memory Circuit Design & Verification Engineer	(4). Product Integration Engineer (PIE)
Scope	1. Memory circuit design and verification. 2. Gate-level verilog simulation against to the datasheet. 3. Failure mode analysis.	1. Drive DRAM product yield improvement. 2. Analyze process and test-related issues and understand DRAM product characteristics. 3. Support test program development activities. 4. Provide production support and participate in new product planning and execution. 5. Conduct failure analysis (FA) activities when required. 6. Improve manufacturing efficiency and reduce product cost
Requirements	1. Experience in SRAM, DRAM, or other memory product design. 2. Solid understanding of digital circuit design and Verilog HDL. 3. Experience with simulation and debugging, able to work independently. 4. Hands-on experience in failure mode analysis is a plus. 5. Deep RTL design experience is not required, but strong gate-level simulation and verification skills are essential.	1. Master's degree in Engineering, Materials Science, Physics, Electrical Engineering, or other related disciplines. 2. Basic knowledge of semiconductor devices, processes, and manufacturing flows. 3. Knowledge of DRAM products and yield improvement methodologies is preferred.

Target Positions & Recommended Student Profiles

(1) Product Engineer (PE)

- 電機、電子、光電、資工相關科系
- 記憶體或半導體相關專題、研究經驗

(2) Product Test Engineer (PTE)

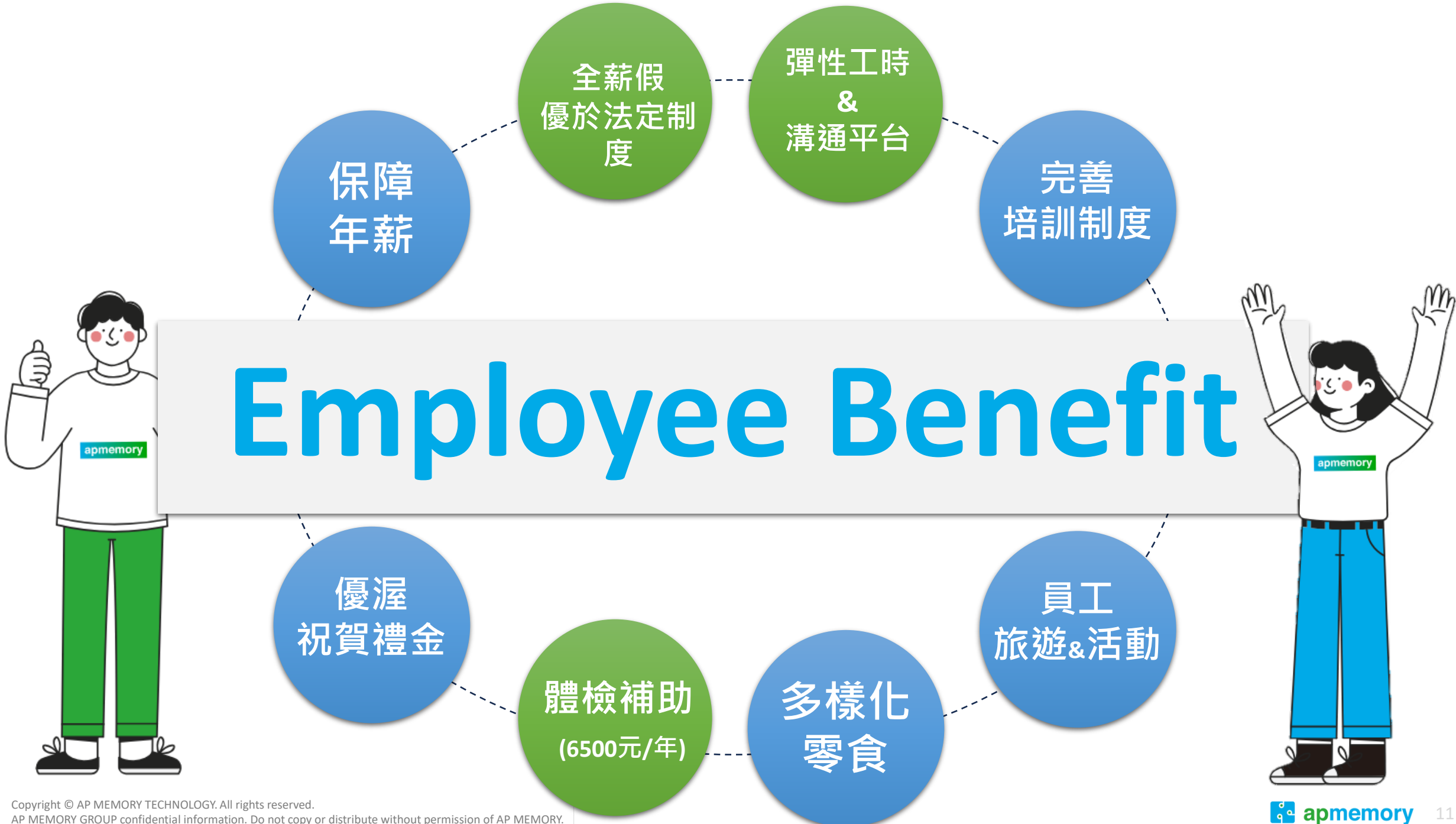
- 電機、電子、光電、資工相關科系
- 對 IC 測試開發有興趣
- 具備基本 C / Python 程式能力

(3) RD - Memory Circuit Design & Verification Engineer

- 電機、電子相關科系
- 半導體電路設計相關專題或研究經驗

(4) Product Integration Engineer (PIE)

- 電機、電子、材料、化工相關科系
- 半導體製程相關專題或研究經驗



研發團隊強力募集中！

#碩博班應屆畢業生

#畢業即就業

#兵役我等你

R&D

| 記憶體IC 設計工程師

Engineering

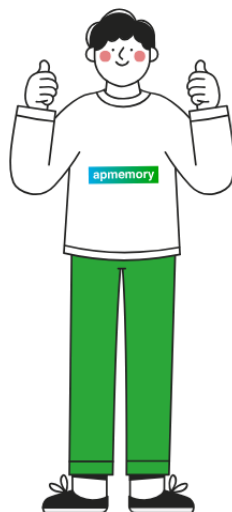
| 產品工程師

| 測試工程師

| 製程整合工程師

掃描右方QR code

將履歷、歷年成績單、專題或碩論等相關
資料，投遞至HR信箱或招募平台



HR 信箱



招募平台



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